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MRF89XAM9A
Data Sheet

915 MHz Ultra Low-Power Sub-GHz
Transceiver Module

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915 MHz Ultra Low-Power Sub-GHz Transceiver Module

Features

- Module designed from the MRF89XA Integrated Ultra Low-Power, Sub-GHz Transceiver IC.
- Supports MiWi™ Development Environment Proprietary Wireless Networking Protocols
- 4-Wire Serial Peripheral Interface (SPI) with Interrupts
- Small Size: 0.7" x 1.1" (17.8 mm x 27.9 mm), Surface Mountable – Pin compatible with MRF89XAM8A
- Integrated Crystal, Internal Voltage Regulator, Matching Circuitry and Printed Circuit Board (PCB) Antenna
- Easy Integration into Final Product – Minimize Product Development, Quicker Time to Market
- Compatible with Microchip's Microcontroller Families (PIC16, PIC18, PIC24, dsPIC33 and PIC32)
- Modular Device Approval for United States (FCC), Canada (IC) and Radio Regulation Certified for Australia/New Zealand (C-TICK)

Operational

- Operating Voltage: 2.1–3.6V (3.3V typical)
- Temperature Range: -40°C to +85°C Industrial
- Low-Current Consumption:
 - Rx mode: 3 mA (typical)
 - Tx mode: 25 mA at +10 dBm (typical)
 - Sleep: 0.1 µA (typical)

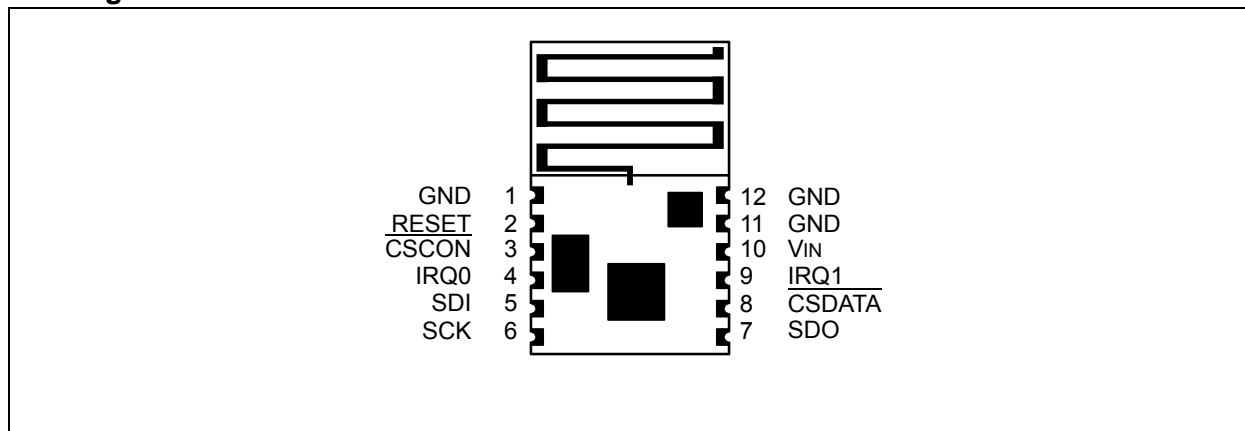
RF/Analog Features

- ISM Band 902–928 MHz Operation
- Modulation: FSK and OOK
- Data Rate:
 - FSK: 200 kbps
 - OOK: 28 kbps
- Reception sensitivity
 - FSK: -105 dBm (typical) at 25 kbps
 - OOK: -111 dBm (typical) at 2 kbps
- +10 dBm Typical Output Power with 21 dB Tx Power Control Range

Media Access Controller (MAC)/ Baseband Features

- Packet handling feature with data whitening and automatic CRC generation
- Incoming sync word (pattern) recognition
- Built-in bit synchronizer for incoming data, and clock synchronization and recovery
- 64-byte transmit/receive FIFO with preload in Stand-by mode
- Supports Manchester encoding/decoding techniques

Pin diagram



MRF89XAM9A

Table of Contents

1.0 Device Overview	3
2.0 Circuit Description	9
3.0 Regulatory Approval	17
4.0 Electrical Characteristics	21
Appendix A: Revision History	27
The Microchip Web Site	29
Customer Change Notification Service	29
Customer Support	29
Reader Response	30
Product Identification System	31

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1.0 DEVICE OVERVIEW

The MRF89XAM9A is an ultra low-power sub-GHz surface mount transceiver module with integrated crystal, internal voltage regulator, matching circuitry and PCB antenna. The MRF89XAM9A module operates in the United States/Canada 902–928 MHz ISM frequency band. The integrated module design frees the integrator from extensive RF and antenna design, and regulatory compliance testing, allowing quicker time to market.

The MRF89XAM9A module is compatible with Microchip's MiWi™ Development Environment software stacks. The software stacks are available as a free download, including source code, from the Microchip's web site <http://www.microchip.com/wireless>.

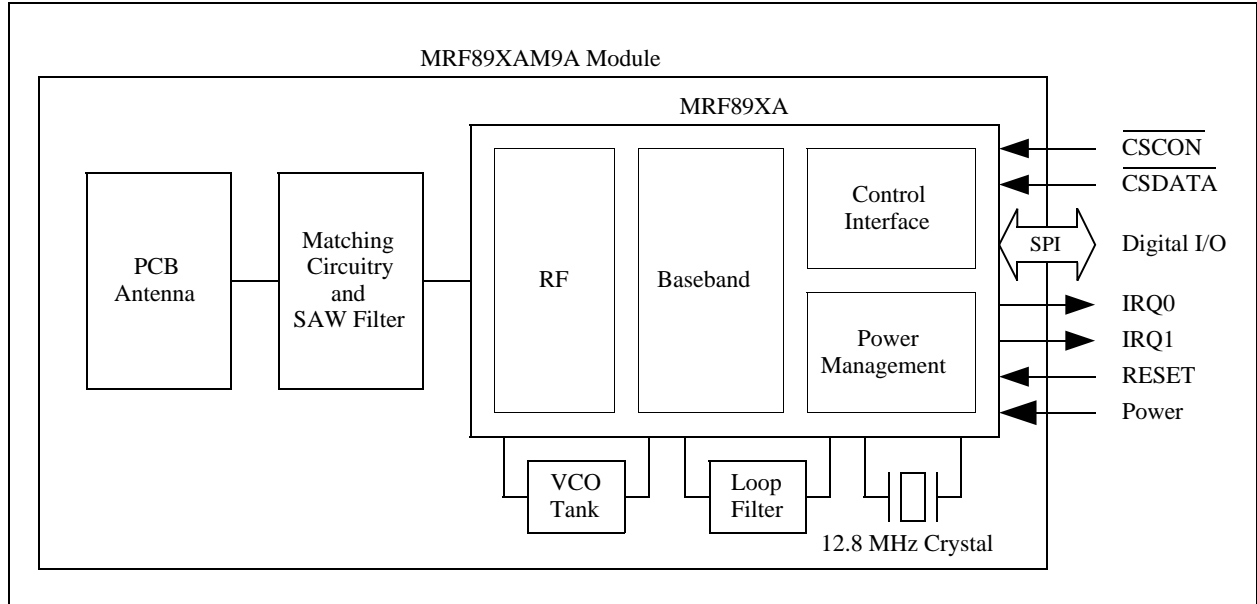
The MRF89XAM9A module has received regulatory approvals for modular devices in the United States (FCC) and Canada (IC). Modular device approval removes the need for expensive RF and antenna design, and allows the user to place the MRF89XAM9A module inside a finished product and not require regulatory testing for an intentional radiator (RF transmitter). To maintain conformance, refer to module settings in [Section 3.1.1, MRF89XAM9A SETTINGS](#) for the United States and [Section 3.2.1, MRF89XAM9A SETTINGS](#) for Canada.

1.1 Interface description

The simplified block diagram of the MRF89XAM9A module is shown in [Figure 1-1](#). The module is based on the Microchip Technology MRF89XA Ultra Low-Power Sub-GHz Transceiver Integrated Circuit (IC). The module interfaces to many popular Microchip PIC® microcontrollers through a 3-wire serial SPI interface, two chip selects (configuration and data), two interrupts Interrupt Request 0 (IRQ0) and Interrupt Request 1 (IRQ1), Reset, Power and Ground as shown in [Figure 1-2](#). [Table 1-1](#) provides the pin descriptions.

Data communication and module configuration are documented in the “*MRF89XA Ultra Low-Power, Integrated Sub-GHz Transceiver*” (DS70622) Data Sheet. For more information on specific serial interface protocol and general register definitions, refer to the “*MRF89XA Data Sheet*” and see [Section 1.3, Operation](#) for specific register settings unique to the MRF89XAM9A module operation to maintain regulatory compliance.

FIGURE 1-1: MRF89XAM9A BLOCK DIAGRAM

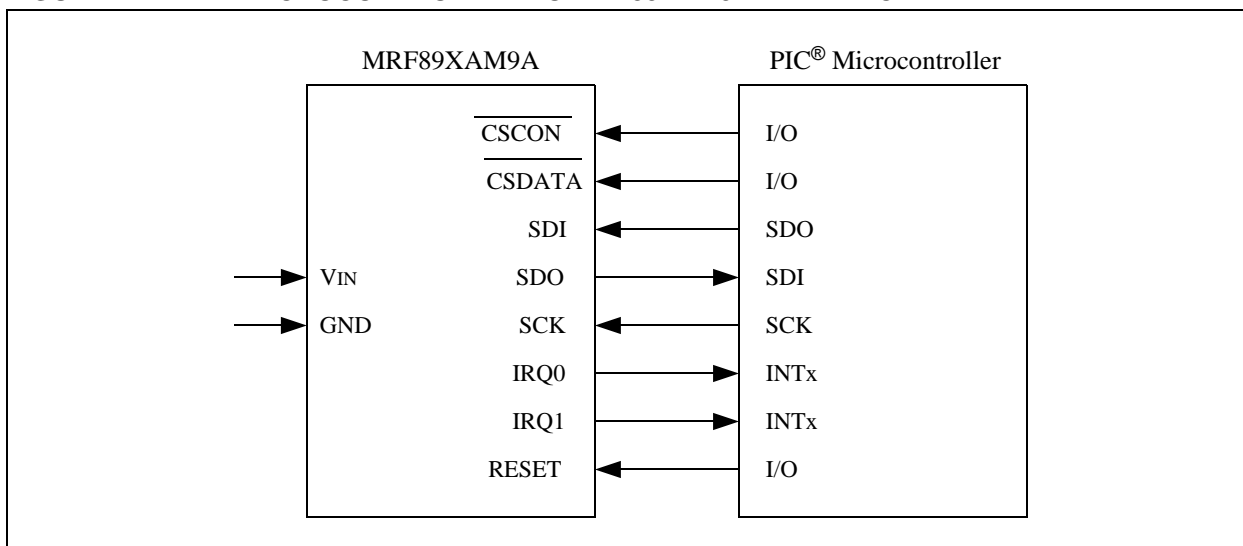


MRF89XAM9A

TABLE 1-1: PIN DESCRIPTION

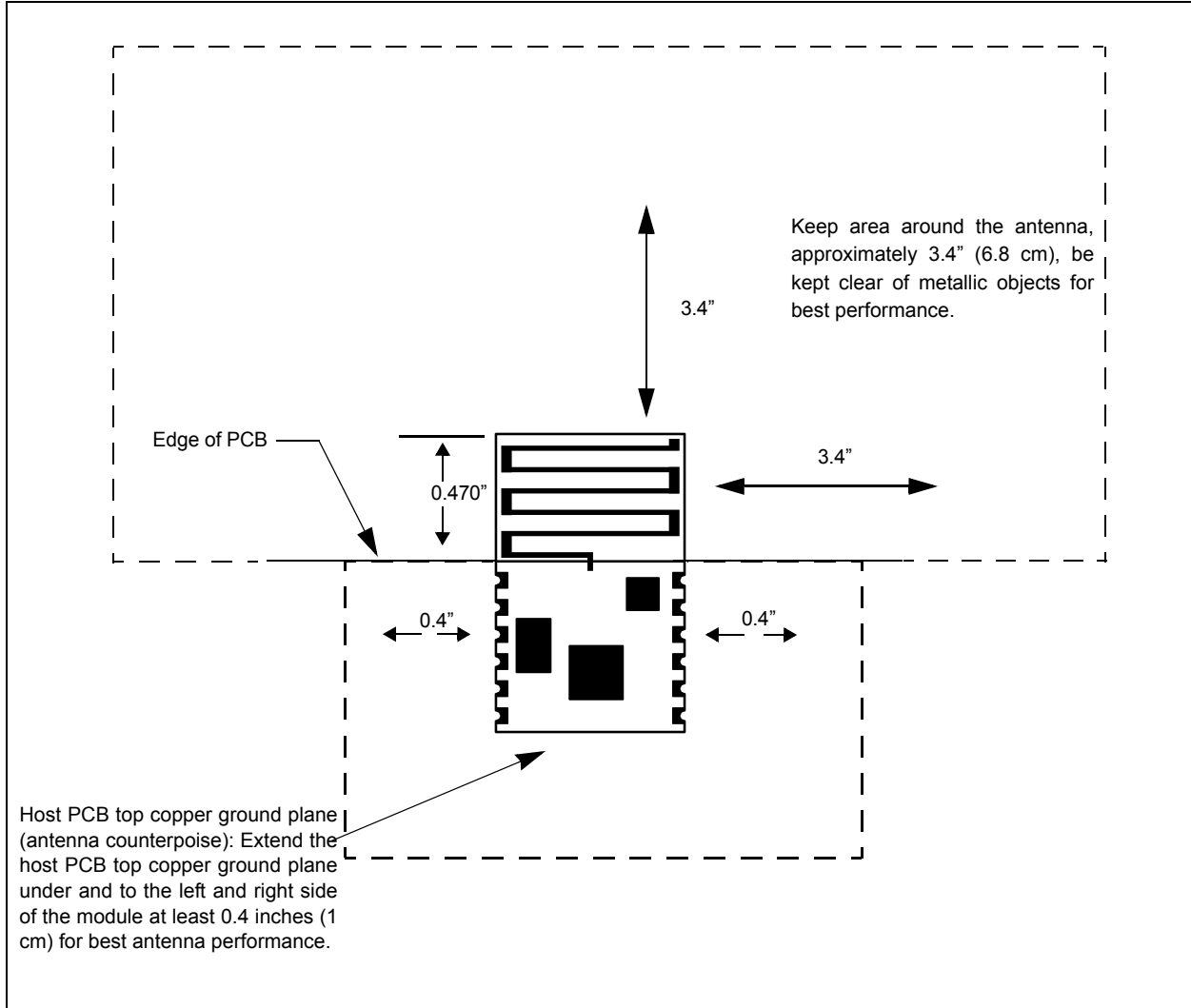
Pin	Symbol	Type	Description
1	GND	Power	Ground
2	RESET	DI	Reset Pin. For more information, refer to Section 1.3.1, Reset
3	CSCON	DI	Serial Interface Configure Chip Select
4	IRQ0	DO	Interrupt Request Output
5	SDI	DI	Serial Interface Data Input
6	SCK	DI	Serial Interface Clock
7	SDO	DO	Serial Interface Data Output
8	CSDATA	DI	Serial Interface Data Chip Select
9	IRQ1	DO	Interrupt Request Output
10	V _{in}	Power	Power Supply
11	GND	Power	Ground
12	GND	Power	Ground

FIGURE 1-2: MICROCONTROLLER TO MRF89XAM9A INTERFACE



MRF89XAM9A

FIGURE 1-5: MOUNTING DETAILS



1.3 Operation

The MRF89XAM9A module is based on the Microchip's MRF89XA Ultra Low-Power, Integrated ISM Band Sub-GHz Transceiver IC. Data communication and module configuration are documented in the "*MRF89XA Ultra Low-Power, Integrated ISM Band Sub-GHz Transceiver Data Sheet*" (DS70622).

This section emphasizes operational settings that are unique to the MRF89XAM9A module design that must be followed for proper operation.

1.3.1 RESET

Pin 2 of the module, RESET, allows an external reset of the MRF89XA IC. RESET is connected to the TEST8 pin of the MRF89XA IC. During normal operations of the MRF89XAM9A, the RESET pin should be held in a high impedance state. For more information on assertion of the RESET pin, refer to "*Section 3.1.2 Manual Reset*" in the "*MRF89XA Data Sheet*" (DS70622).

1.3.2 CRYSTAL FREQUENCY

When calculating frequency deviation, bit rate, receiver bandwidth, and PLL R, P and S values, use crystal frequency $f_{xtal} = 12.8$ MHz.

1.3.3 CLOCK OUTPUT (CLKOUT)

The CLKOUT pin 19 of the MRF89XA IC is not used on the module. Ensure that the CLKOUT signal is disabled to minimize current consumption.

1.3.4 FREQUENCY BAND SELECT

The Frequency Band Select (FBS<1:0>) bits in the GCONREG<4:3> should be set for target channel range 902–915 MHz FBS<1:0> = '00' or 915–928 MHz FBS<1:0> = '01'.

1.3.5 VCO TANK TRIM VALUE

The VCO Trim (VCOT<1:0>) bits in the GCONREG<2:1> should be set for VCOT<1:0> = '01' for the inductor values of the module.

1.3.6 BIT RATE

The maximum bit rate value will be limited to 28 kbps for OOK modulation due to the crystal frequency of 12.8 MHz.

MRF89XAM9A

NOTES:

2.0 CIRCUIT DESCRIPTION

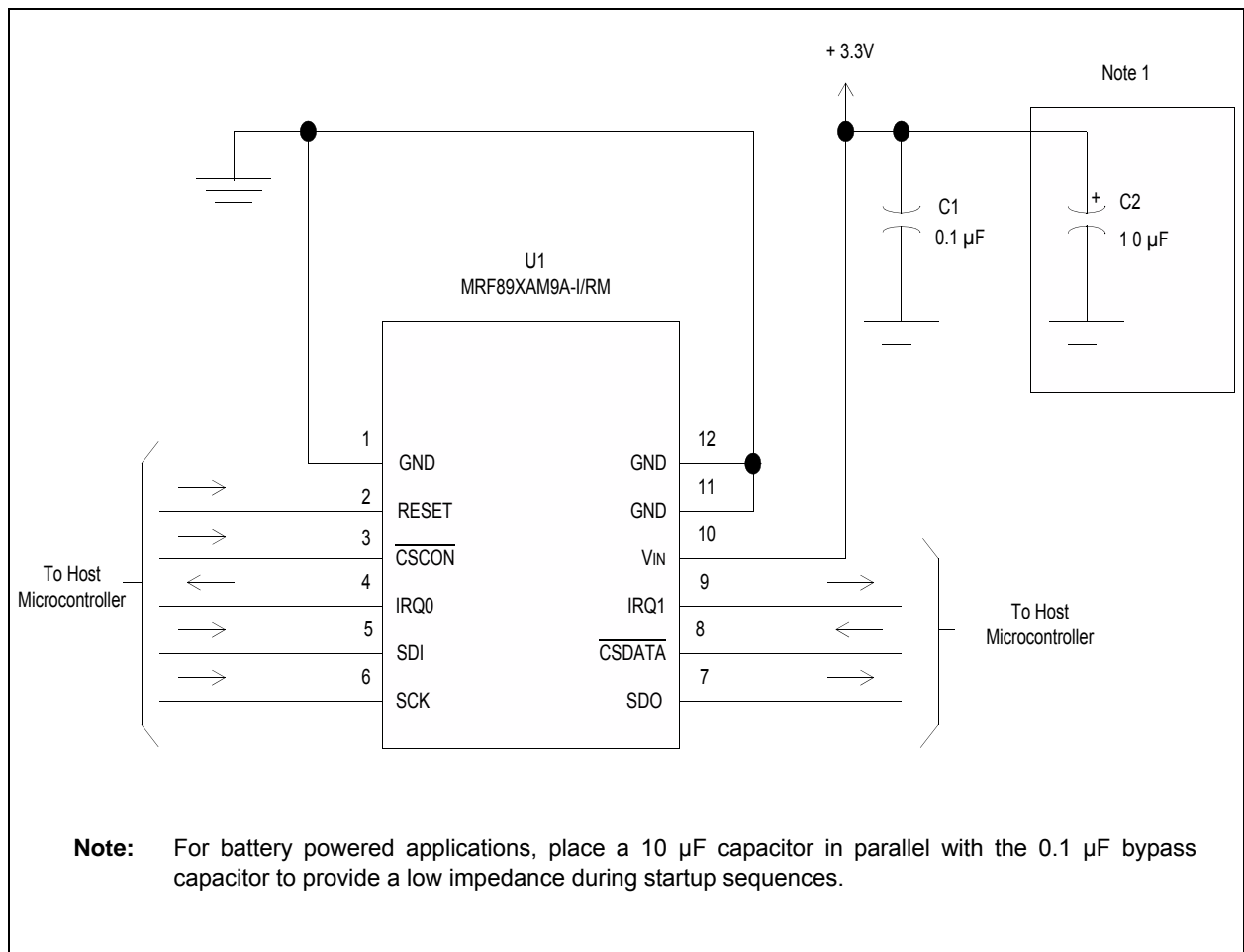
The MRF89XAM9A module interfaces to Microchip's PIC16, PIC18, PIC24, dsPIC33 and PIC32 microcontrollers with a minimum of external components through digital only connections. An example application schematic is shown in [Figure 2-2](#).

2.1 Module Schematic

The MRF89XAM9A module is based on the Microchip's MRF89XA Ultra Low-Power, Integrated ISM Band Sub-GHz Transceiver IC. The serial I/O (CSCON, CSDATA, SCK, SDO and SDI), RESET, IRQ0 and IRQ1 pins are routed out and available on the module pins as shown in [Figure 2-2](#). Crystal X1 is a 12.8 MHz crystal with a frequency tolerance of ± 10 ppm at 25°C. The RFIO output is matched to the SAW filter FL1 and further matched to the PCB trace antenna.

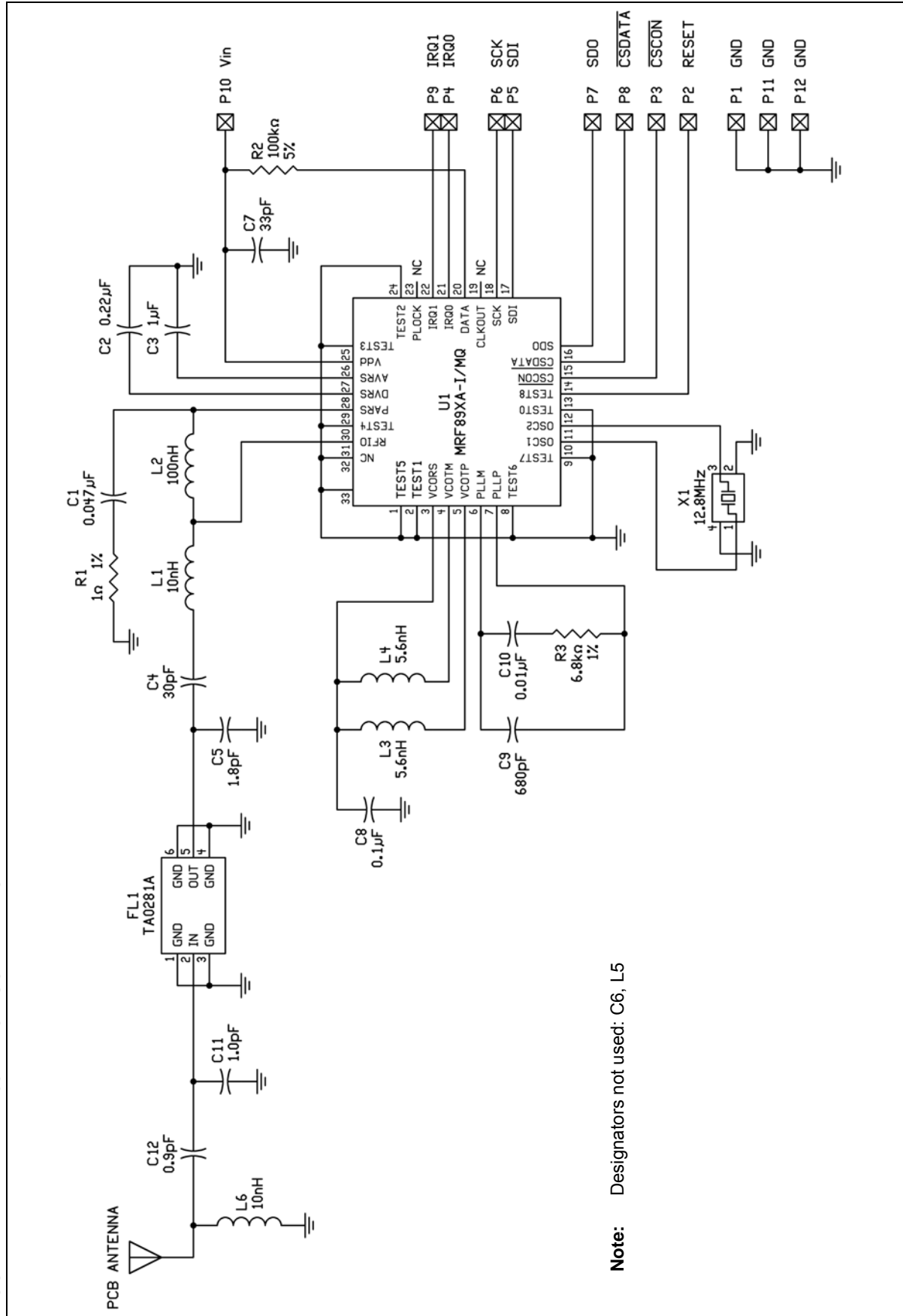
[Figure 2-2](#) illustrates the MRF89XAM9A schematics. [Table 2-1](#) details the Bill of Materials (BOM).

FIGURE 2-1: MRF89XAM9A APPLICATION SCHEMATIC



MRF89XAM9A

FIGURE 2-2: MRF89XAM9A SCHEMATIC



Note: Designators not used: C6, L5

MRF89XAM9A

TABLE 2-1: MRF89XAM9A BILL OF MATERIALS

Designator	Value	Description	Manufacturer	Part Number
C1	0.047 μ F	Capacitor, Ceramic, 10V, \pm 10%, X7R, SMT 0402	Murata	GRM155R71A473KA01D
C2	0.22 μ F	Capacitor, Ceramic, 16V, \pm 10%, X7R, SMT 0402	Murata	GRM155R71C224KA12D
C3	1 μ F	Capacitor, Ceramic, 6.3V, \pm 10%, X5R, SMT 0603	Murata	GRM188R60J105KA01D
C4	30 pF	Capacitor, Ceramic, 50V, \pm 5%, UHI-Q NP0, SMT 0402	Johanson Technology	250R07S300JV4T
C5	1.8 pF	Capacitor, Ceramic, 50V, \pm 0.1 pF, UHI-Q NP0, SMT 0402	Johanson Technology	500R07S1R8BV4
C6	—	Designator not used	—	—
C7	33 pF	Capacitor, Ceramic, 50V, \pm 5%, C0G, SMT 0402	Murata	GRM1555C1H330JZ01D
C8	0.1 μ F	Capacitor, Ceramic, 16V, \pm 10%, X7R, SMT 0402	Murata	GRM155R71C104KA88D
C9	680 pF	Capacitor, Ceramic, 50V, \pm 5%, C0G, SMT 0402	Murata	GRM1555C1H681JA01D
C10	0.01 μ F	Capacitor, Ceramic, 16V, \pm 10%, X7R, SMT 0402	Murata	GRM155R71C103KA01D
C11	1.0 pF	Capacitor, Ceramic, 50V, \pm 0.1 pF, UHI-Q NP0, SMT 0402	Johanson Technology	500R07S1R0BV4
C12	0.9 pF	Capacitor, Ceramic, 50V, \pm 0.1 pF, UHI-Q NP0, SMT 0402	Johanson Technology	500R07S0R9BV4
FL1	TA0281A	Filter, SAW, 902–928 MHz	Tai-saw Technology	TA0281A
L1	10 nH	Inductor, Ceramic, \pm 5%, SMT 0402	Johanson Technology	L-07C10NJV6T
L2	100 nH	Inductor, Ceramic, \pm 5%, SMT 0402	Johanson Technology	L-07CR10JV6T
L3	5.6 nH	Inductor, Wirewound, \pm 5%, SMT 0402	Johanson Technology	L-07W5N6JV4T
L4	5.6 nH	Inductor, Wirewound, \pm 5%, SMT 0402	Johanson Technology	L-07W5N6JV4T
L5	—	Designator not used	—	—
L6	10 nH	Inductor, Ceramic, \pm 5%, SMT 0402	Johanson Technology	L-07C10NJV6T
R1	1 Ω	Resistor, 1%, \pm 100 ppm/ $^{\circ}$ C, SMT 0402	Vishay/Dale	CRCW04021R00FKED
R2	100K Ω	Resistor, 5%, \pm 100 ppm/ $^{\circ}$ C, SMT 0402	Yageo	RC0402JR-07100KL
R3	6.8K Ω	Resistor, 1%, \pm 100 ppm/ $^{\circ}$ C, SMT 0402	Yageo	RC0402FR-076K8L
U1	MRF89XA	Transceiver, Ultra Low-Power, Integrated Sub-GHz	Microchip Technology	MRF89XA-I/MQ
X1	12.8 MHz	Crystal, \pm 10 ppm, 15 pF, ESR 100 ohms, SMT 5 x 3.2mm	Abracon	ABM3B-155-12.800MHz-T

MRF89XAM9A

2.2 Printed Circuit Board

The MRF89XAM9A module PCB is constructed with high temperature FR4 material that is four layers and 0.032 inches thick. The layers are shown in Figure 2-3 through Figure 2-8. The PCB layer stack up is shown in Figure 2-9

FIGURE 2-3: TOP SILK SCREEN

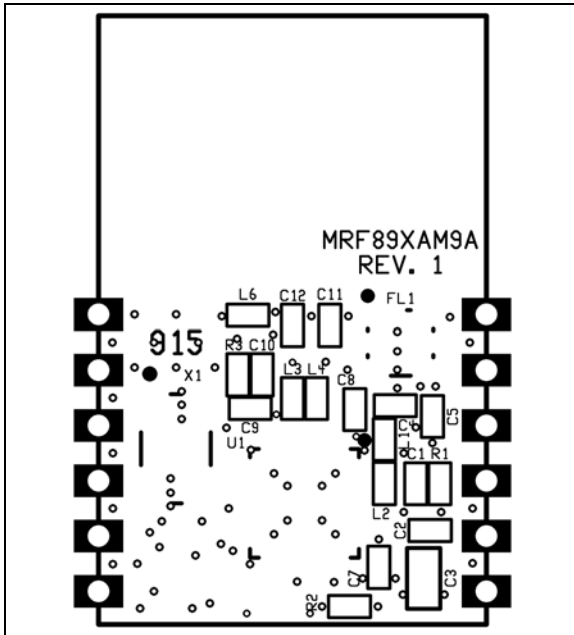


FIGURE 2-4: TOP COPPER

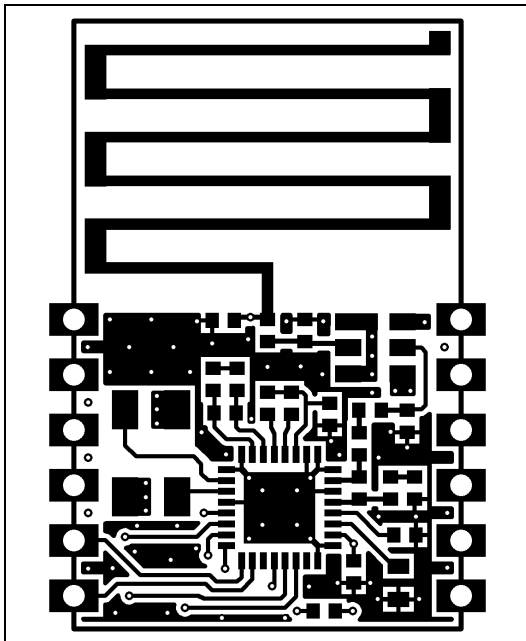


FIGURE 2-5: LAYER 2 — GROUND PLANE

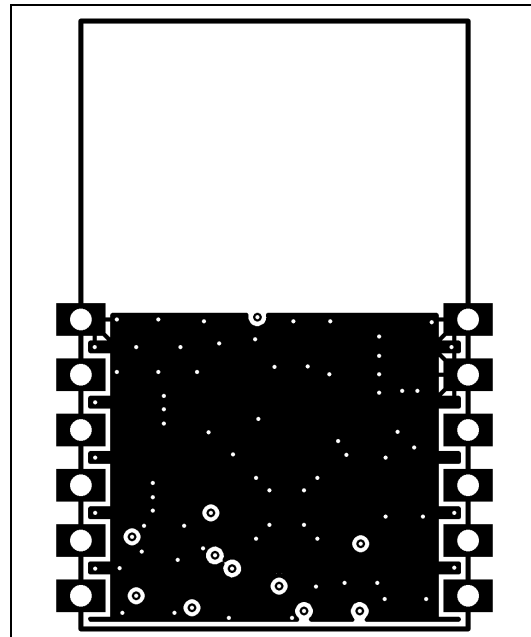


FIGURE 2-6: LAYER 3 — POWER PLANE

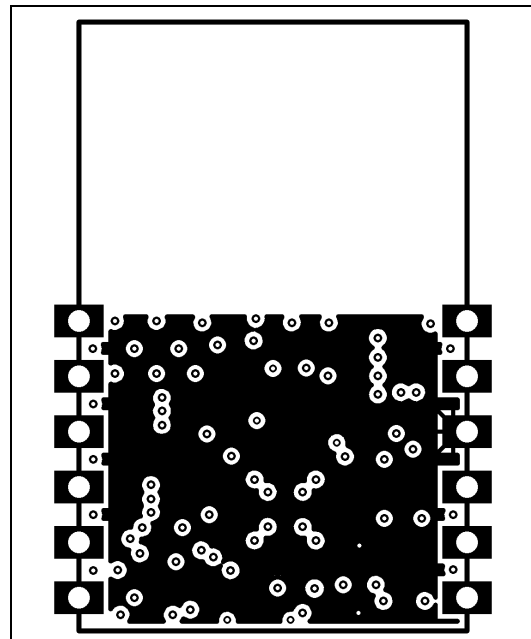


FIGURE 2-7: BOTTOM COPPER

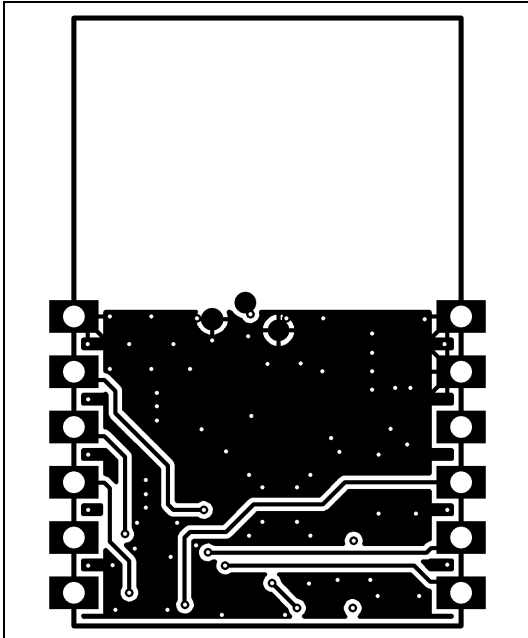


FIGURE 2-8: BOTTOM SILK SCREEN

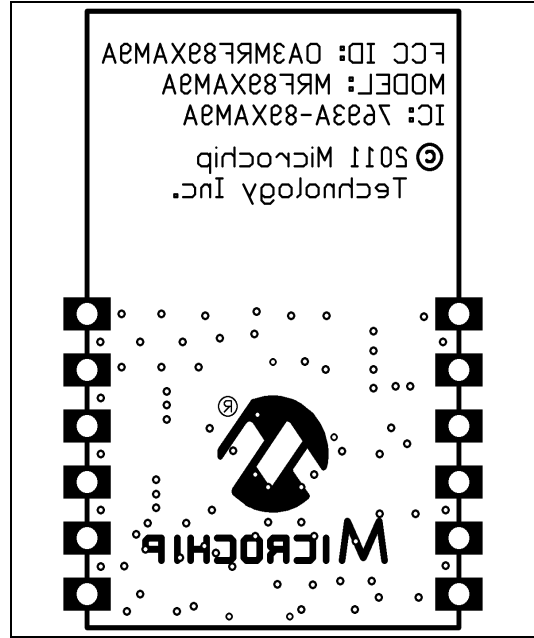
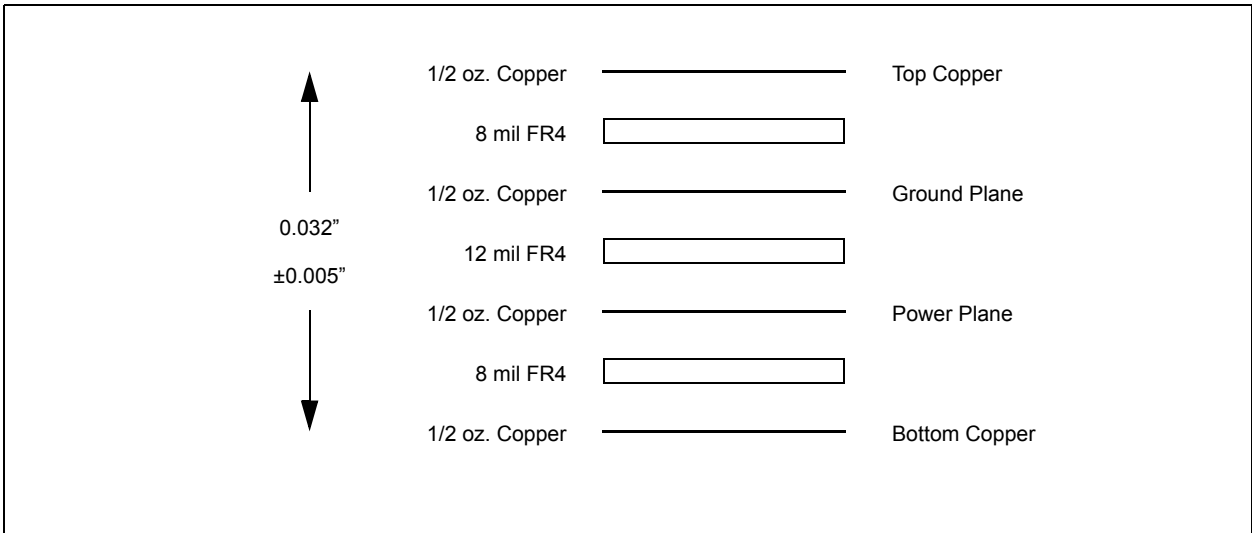


FIGURE 2-9: PCB LAYER STACK UP



MRF89XAM9A

2.3 PCB Antenna

The PCB antenna is fabricated on the top copper trace. [Figure 2-10](#) shows the PCB antenna dimensions. The layers below the antenna have no copper traces. The ground and power planes under the components serve as a counterpoise to the PCB antenna. Additional ground plane on the host PCB will substantially enhance the performance of the module. For best performance, place the module on the host PCB by following the recommendations in [Section 1.2, Mounting Details](#).

The PCB antenna was designed and simulated using Ansoft Designer[®] and HFSS[™] 3D full-wave solver software by ANSYS, Inc. (www.ansoft.com). The goal of the design was to create a compact, low-cost antenna with the best radiation pattern. [Figure 2-11](#) shows the PCB antenna simulation drawing and [Figure 2-12](#) and [Figure 2-13](#) show the simulated 2D and 3D radiation patterns. As shown by the radiation patterns, the performance of the antenna is dependant upon the orientation of the module. [Figure 2-14](#) shows the impedance simulation and [Figure 2-15](#) shows the actual impedance measurement. The discrete

matching circuitry matches the impedance of the antenna with the SAW filter and MRF89XA transceiver IC.

FIGURE 2-10: PCB ANTENNA DIMENSIONS

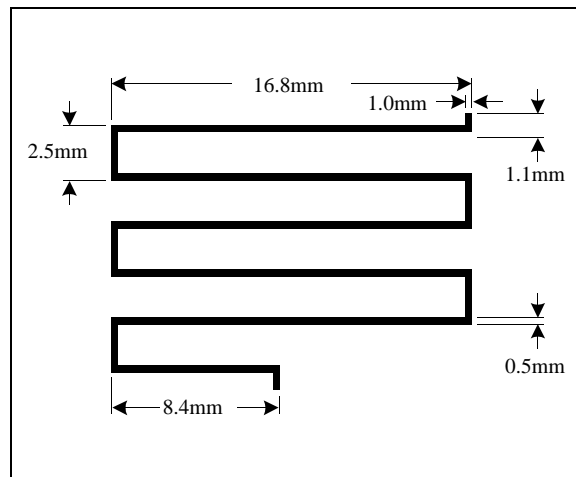


FIGURE 2-11: PCB ANTENNA SIMULATION DRAWING

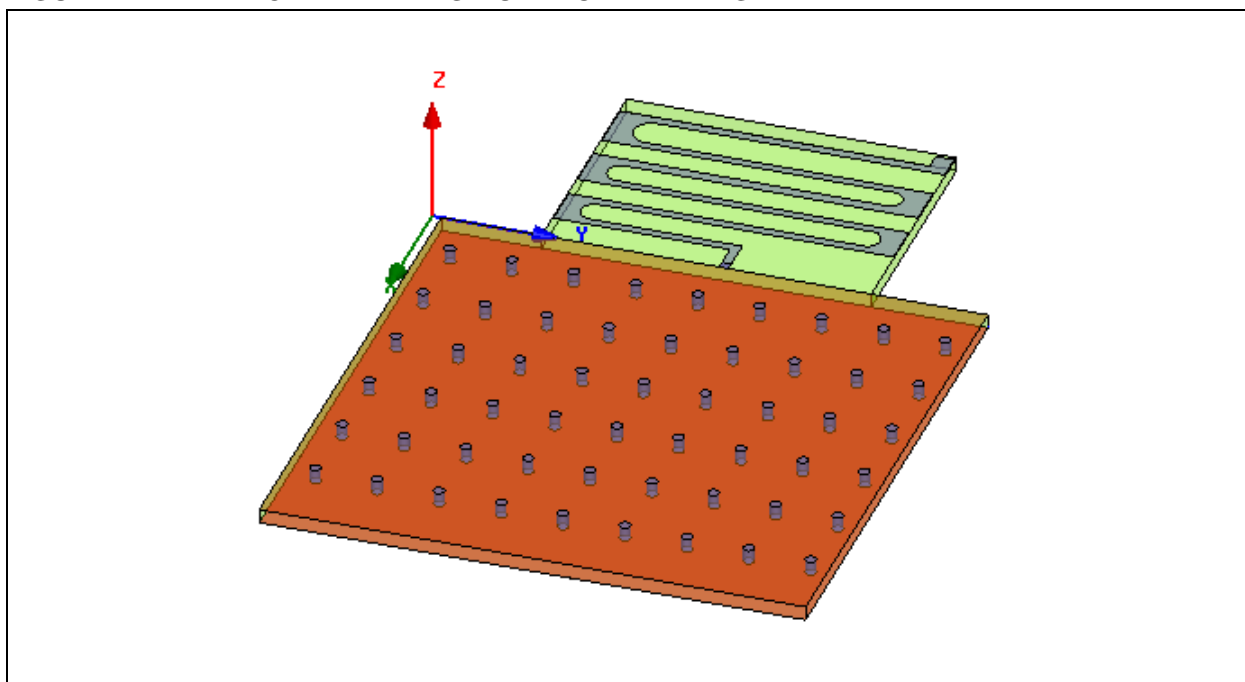


FIGURE 2-12: SIMULATED 2D RADIATION PATTERN

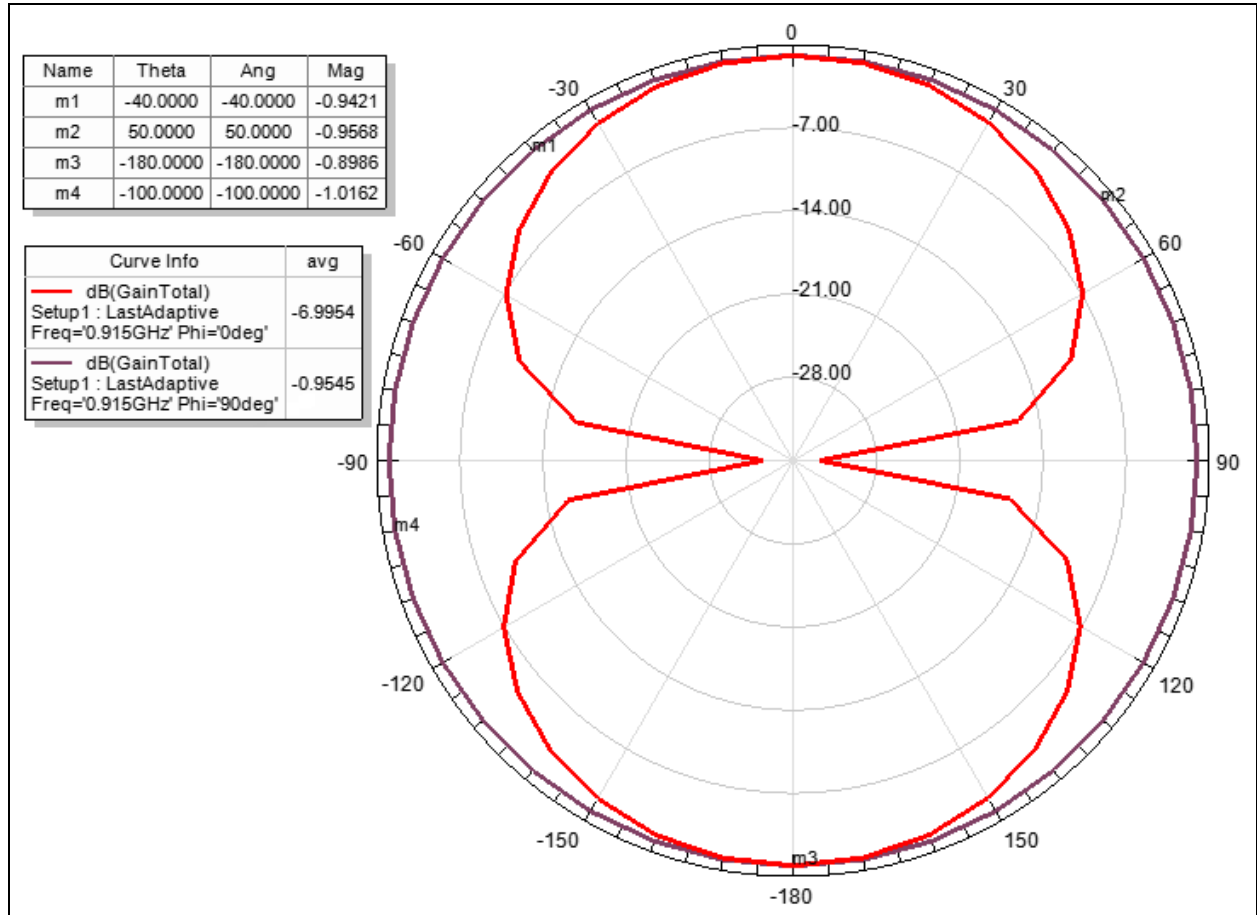
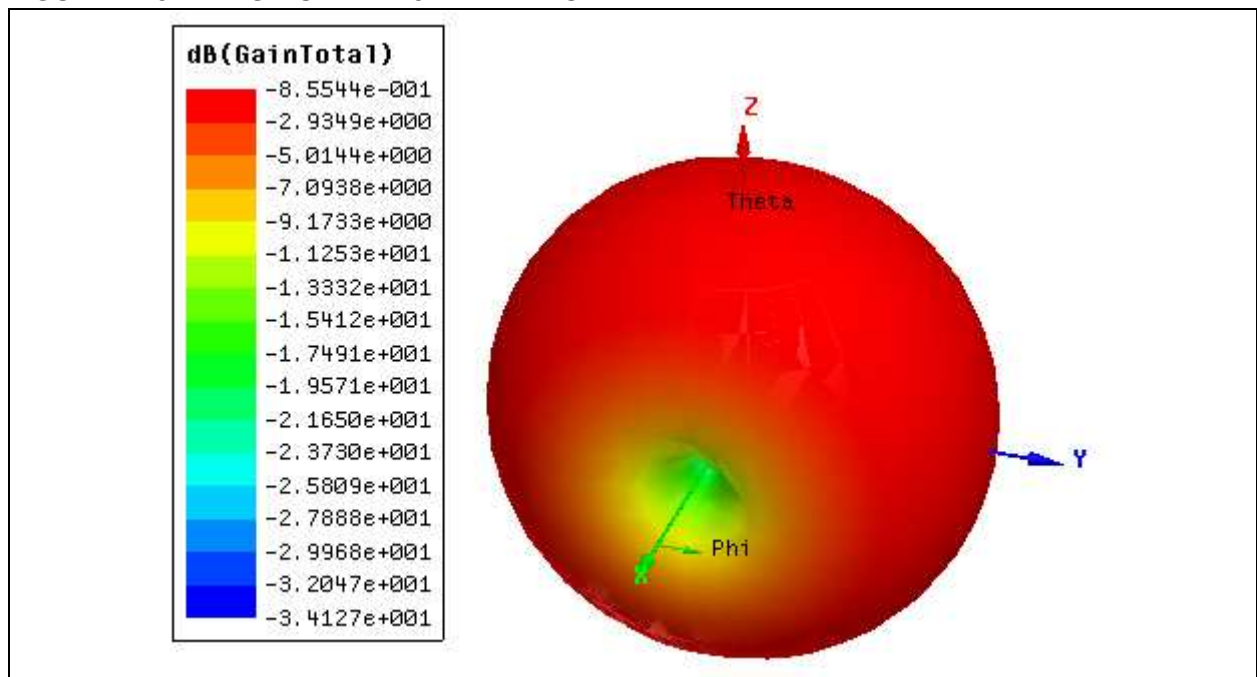


FIGURE 2-13: SIMULATED 3D RADIATION PATTERN



MRF89XAM9A

FIGURE 2-14: SIMULATED PCB ANTENNA IMPEDANCE

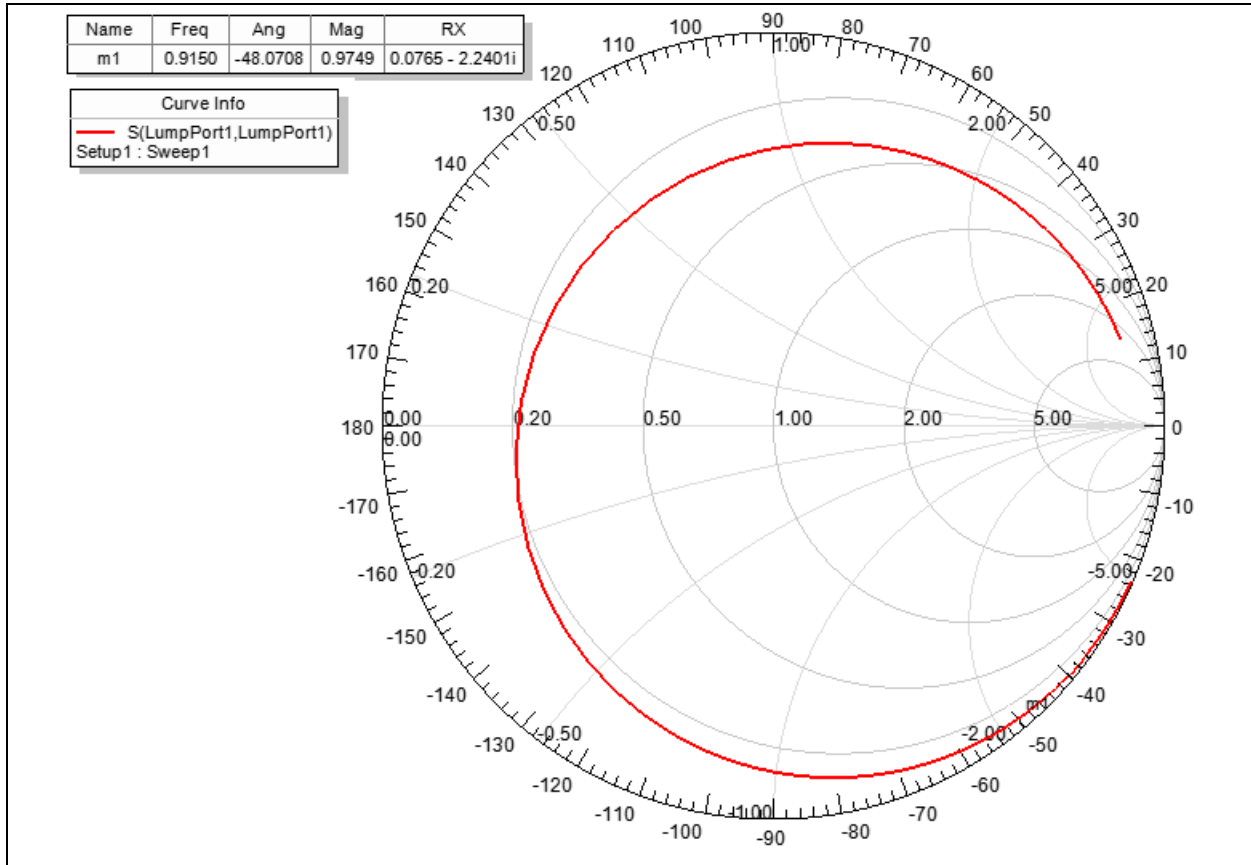
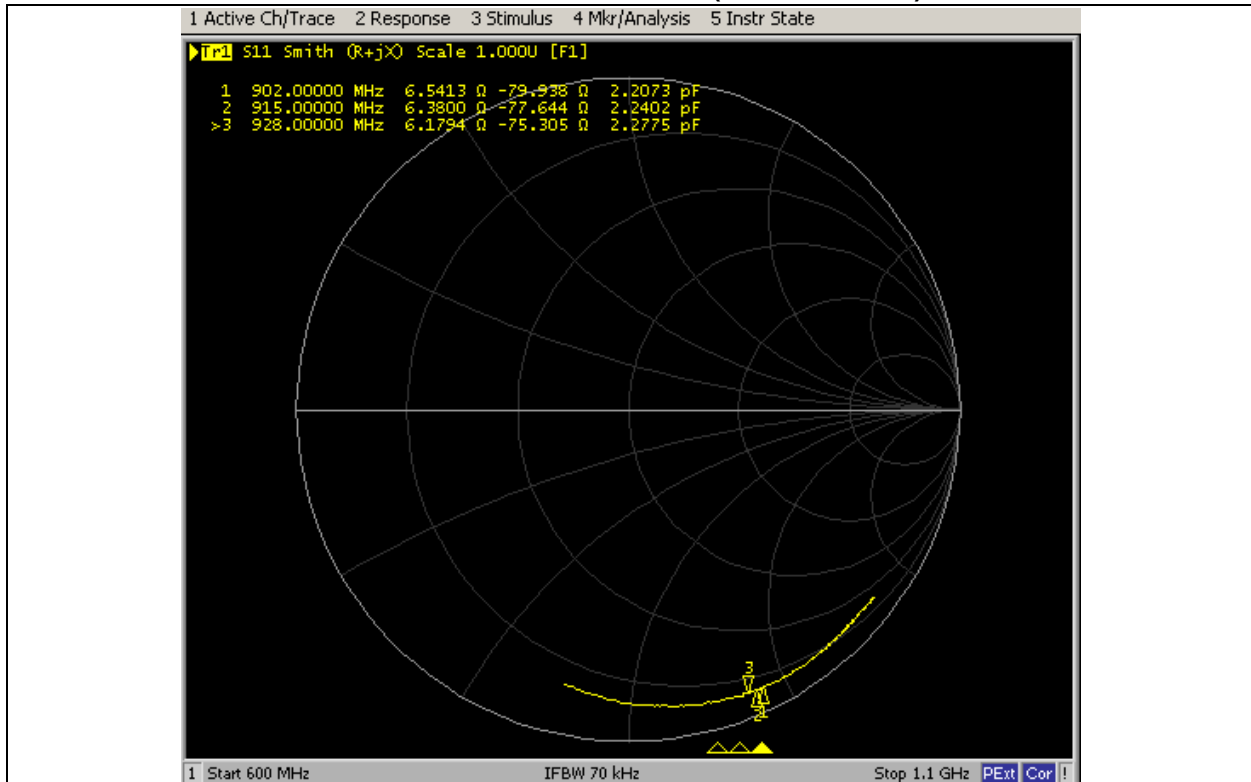


FIGURE 2-15: MEASURED ANTENNA IMPEDANCE (915 MHZ BAND)



3.0 REGULATORY APPROVAL

The MRF89XAM9A module has received regulatory approvals for modular devices in the United States and Canada. Modular device approval allows the end user to place the MRF89XAM9A module inside a finished product and not require regulatory testing for an intentional radiator (RF transmitter), provided no changes or modifications are made to the module circuitry. Changes or modifications could void the user's authority to operate the equipment. The end user must comply with all of the instructions provided by the Grantee, which indicate installation and/or operating conditions necessary for compliance.

The integrator is still responsible for testing the end product for any additional compliance requirements required with this module installed (digital device emission, PC peripheral requirements, etc.) in the specific country that the end device will be marketed.

For more information on regulatory compliance, refer to the specific country radio regulations in the following sections.

3.1 United States

The MRF89XAM9A has received Federal Communications Commission (FCC) CFR47 Telecommunications, Part 15 Subpart C "Intentional Radiators" 15.247 and 15.249 and modular approval in accordance with Part 15.212 Modular Transmitter approval. The MRF89XAM9A module can be integrated into a finished product without obtaining subsequent and separate FCC certification.

The MRF89XAM9A module has been labeled with its own FCC ID number, and if the FCC ID is not visible when the module is installed inside another device, then the outside of the finished product into which the module is installed must also display a label referring to the enclosed module. This exterior label can use wording as following:

Contains Transmitter Module FCC ID:
OA3MRF89XAM9A
-or-
Contains FCC ID: OA3MRF89XAM9A
This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions:
(1) this device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Requirements for product labeling are given in Part 15.19 Labeling Requirements.

The user's manual should include the following statement:

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy, and if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment OFF and ON, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

3.1.1 MRF89XAM9A SETTINGS

To meet the FCC requirements, the following settings must be observed by the integrator:

3.1.1.1 FSK Modulation

The following settings configure the MRF89XAM9A for wideband digital modulation techniques that conform to the requirements of Part 15.247. These settings allow higher radio frequency (RF) output power and greater link budget:

- Bit Rate Setting: 50 - 200 kbps
 - Transmit Power Maximum Setting: 13 dBm
- Bit Rate Setting: 2 - 40 kbps
 - Transmit Power Maximum Setting: 7 dBm
- Frequency Deviation Setting: 200 kHz
- Data Whitening: On
- Lower Frequency Setting: 902.800 MHz
- Upper Frequency Setting: 926.500 MHz

MRF89XAM9A

3.1.1.2 OOK Modulation

The following settings configure the MRF89XAM9A for narrowband operation that conform to the requirements of the part 15.249. The part 15.249 requires a much lower power setting than it is allowed in the part 15.247. These settings are good for applications that require lower transmit power current consumption and shorter transmit distances:

- Transmit Power Maximum Setting: 1 dBm
- Bit Rate Maximum Setting: 28 kbps
- Frequency Deviation Setting: 200 kHz
- Lower Frequency Setting: 902.330 MHz
- Upper Frequency Setting: 927.500 MHz

3.1.2 RF EXPOSURE

All transmitters regulated by FCC must comply with RF exposure requirements. OET Bulletin 65 "*Evaluating Compliance with FCC Guidelines for Human Exposure to Radio Frequency Electromagnetic Fields*" provides assistance in determining whether proposed or existing transmitting facilities, operations or devices comply with limits for human exposure to RF fields adopted by the Federal Communications Commission (FCC). The bulletin offers guidelines and suggestions for evaluating compliance.

If appropriate, compliance with exposure guidelines for mobile and unlicensed devices can be accomplished by using warning labels and by providing informations concerning minimum separation distances from transmitting structures and proper installation of antennas.

The following statement must be included as a CAUTION statement in manuals and OEM products to alert users of FCC RF Exposure compliance:

To satisfy FCC RF Exposure requirements for mobile and base station transmission devices, a separation distance of 20 cm or more should be maintained between the antenna of this device and persons during operation. To ensure compliance, operation at closer than this distance is not recommended.

The antenna(s) used for this transmitter must not be co-located or operating in conjunction with any other antenna or transmitter.

If the MRF89XAM9A module is used in a portable application (antenna is less than 20 cm from persons during operation), the integrator is responsible for performing Specific Absorption Rate (SAR) testing in accordance with FCC rules 2.1091.

3.1.3 HELPFUL WEB SITES

Federal Communications Commission (FCC) <http://www.fcc.gov>

3.2 Canada

The MRF89XAM9A module has been certified for use in Canada under Industry Canada (IC) Radio Standards Specification (RSS) RSS-210 and RSS-Gen. Modular approval permits the installation of a module in a host device without the need to recertify the device.

Labeling Requirements for the Host Device (from Section 3.2.1, RSS-Gen, Issue 3, December 2010):

The host device must be labeled to identify the module within the host device.

The Industry Canada certification label of a module shall be clearly visible at all times when installed in the host device, otherwise the host device must be labeled to display the Industry Canada certification number of the module, preceded by the words "Contains transmitter module", or the word "Contains", or similar wording expressing the same meaning, as follows:

Contains transmitter module IC: 7693A-89XAM9A

User Manual Notice for License-Exempt Radio Apparatus (from Section 7.1.3 RSS-Gen, Issue 3, December 2010):

User manuals for license-exempt radio apparatus must contain the following or equivalent notice in a conspicuous location in the user manual or alternatively on the device or both.

This device complies with Industry Canada license-exempt RSS standard(s). Operation is subject to the following two conditions: (1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes: (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

3.2.1 MRF89XAM9A SETTINGS

To meet Industry Canada (IC) requirements, the following settings must be observed by the integrator:

3.2.1.1 FSK Modulation

The following settings configure the MRF89XAM9A for wideband digital modulation techniques that conform to the requirements of RSS-210 Issue 8, Annex 8. These settings allow higher radio frequency (RF) output power and greater link budget.

- Bit Rate Setting: 50–200 kbps
 - Transmit Power Maximum Setting: 13 dBm
- Bit Rate Setting: 2–40 kbps
 - Transmit Power Maximum Setting: 7 dBm
- Frequency Deviation Setting: 200 kHz
- Data Whitening: On
- Lower Frequency Setting: 902.800 MHz
- Upper Frequency Setting: 926.500 MHz

3.2.1.2 OOK Modulation

The following settings configure the MRF89XAM9A for narrowband operation that conform to the requirements of RSS-Gen Issue 3. RSS-Gen Issue 3 requires a much lower power setting than is allowed in Part RSS-210 Issue 8 Annex 8. These settings are good for applications that require lower transmit power current consumption and shorter transmit distances.

- Transmit Power Maximum Setting: 1 dBm
- Bit Rate Maximum Setting: 28 kbps
- Frequency Deviation Setting: 200 kHz
- Lower Frequency Setting: 902.330 MHz
- Upper Frequency Setting: 927.500 MHz

3.2.2 HELPFUL WEB SITES

Industry Canada: <http://www.ic.gc.ca/>

MRF89XAM9A

NOTES:

4.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings

Ambient temperature under bias	-40°C to +85°C
Storage temperature	-55°C to +125°C
Voltage on VIN with respect to VSS	-0.3V to 6V
Voltage on any combined digital and analog pin with respect to VSS (except VIN)	-0.3V to (VIN + 0.3V)
Input current into pin (except VIN and VSS).....	-25 mA to 25 mA

NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

MRF89XAM9A

TABLE 4-1: RECOMMENDED OPERATING CONDITIONS

Parameter	Min	Typ	Max	Unit	Condition
Ambient Operating Temperature	-40	—	+85	°C	—
Supply Voltage for RF, Analog and Digital Circuits	2.1	—	3.6	V	—
Supply Voltage for Digital I/O	2.1	—	3.6	V	—
Input High Voltage (V _{IH})	0.5 * V _{IN}	—	V _{IN} + 0.3	V	—
Input Low Voltage (V _{IL})	-0.3V	—	0.2 * V _{IN}	V	—
AC Peak Voltage on Open Collector Outputs (I _O) ⁽¹⁾	V _{IN} - 1.5	—	V _{IN} + 1.5	V	—

Note 1: At minimum, V_{IN} - 1.5V should not be lower than 1.8V.

TABLE 4-2: CURRENT CONSUMPTION

Symbol	Chip Mode	Min	Typ	Max	Unit	Condition
IDDSL	Sleep	—	0.1	2	µA	Sleep clock disabled, all blocks disabled
IDDST	Idle	—	65	80	µA	Oscillator and baseband enabled
IDDFS	Frequency Synthesizer	—	1.3	1.7	mA	Frequency synthesizer running
IDDTX	Tx	—	25 16	30 21	mA mA	Output power = +10 dBm Output power = +1 dBm ⁽¹⁾
IDDRX	Rx	—	3.0	3.5	mA	—

Note 1: Guaranteed by design and characterization.

TABLE 4-3: DIGITAL I/O PIN INPUT SPECIFICATIONS⁽¹⁾

Symbol	Characteristic	Min	Typ	Max	Unit	Condition
V _{IL}	Input Low Voltage	—	—	0.2 * V _{IN}	V	—
V _{IH}	Input High Voltage	0.8 * V _{IN}	—	—	V	—
I _{IL}	Input Low Leakage Current ⁽²⁾	-0.5	—	0.5	µA	V _{IL} = 0V
I _{IH}	Input High Leakage Current	-0.5	—	0.5	µA	V _{IH} = V _{IN} , V _{IN} = 3.7
V _{OL}	Digital Low Output Voltage	—	—	0.1 * V _{IN}	—	I _{OL} = 1 mA
V _{OH}	Digital Low Output	0.9 * V _{IN}	—	—	V	I _{OH} = -1 mA

Note 1: Measurement Conditions: T_A = 25°C, V_{IN} = 3.3V, Crystal Frequency = 12.8 MHz, unless otherwise specified.

2: Negative current is defined as the current sourced by the pin.

TABLE 4-4: PLL PARAMETERS AC CHARACTERISTICS⁽¹⁾

Symbol	Parameter	Min	Typ	Max	Unit	Condition
FRO	Frequency Ranges	902	—	928	MHz	—
BRFSK	Bit Rate (FSK)	2	—	200	kbps	NRZ
BROOK	Bit Rate (OOK)	1.56	—	28	kbps	NRZ
FDFSK	Frequency Deviation (FSK)	33	—	200	kHz	—
FXTAL	Crystal Oscillator Frequency	—	12.8	—	MHz	—
FSSTP	Frequency Synthesizer Step	—	2	—	kHz	Variable, depending on the frequency
TSOSC	Oscillator Wake-up Time	—	1.5	5	ms	From Sleep mode ⁽¹⁾
TSFS	Frequency Synthesizer Wake-up Time; at most, 10 kHz away from the target	—	500	800	μs	From Stand-by mode
TSHOP	Frequency Synthesizer Hop Time; at most, 10 kHz away from the target	—	180	—	μs	200 kHz step
		—	200	—	μs	1 MHz step
		—	250	—	μs	5 MHz step
		—	260	—	μs	7 MHz step
		—	290	—	μs	12 MHz step
		—	320	—	μs	20 MHz step
		—	340	—	μs	27 MHz step

Note 1: Guaranteed by design and characterization.

MRF89XAM9A

TABLE 4-5: RECEIVER AC CHARACTERISTICS⁽¹⁾

Symbol	Parameter	Min	Typ	Max	Unit	Condition
RSF	Sensitivity (FSK)	—	-105	—	dBm	915 MHz, BR = 25 kbps, $f_{dev} = 50$ kHz, $f_c = 100$ kHz
		—	-101	—	dBm	915 MHz, BR = 66.7 kbps, $f_{dev} = 100$ kHz, $f_c = 200$ kHz
RSO	Sensitivity (OOK)	—	-111	—	dBm	915 MHz, 2 kbps NRZ $f_c - f_o = 50$ kHz, $f_o = 50$ kHz
		—	-105	—	dBm	915 MHz, 16.7 kbps NRZ $f_c - f_o = 100$ kHz, $f_o = 100$ kHz
CCR	Co-Channel Rejection	—	-12	—	dBc	Modulation as wanted signal
ACR	Adjacent Channel Rejection	—	27	—	dB	Offset = 300 kHz, unwanted tone is not modulated
		—	52	—	dB	Offset = 600 kHz, unwanted tone is not modulated
		—	57	—	dB	Offset = 1.2 MHz, unwanted tone is not modulated
BI	Blocking Immunity	—	-48	—	dBm	Offset = 1 MHz, unmodulated
		—	-37	—	dBm	Offset = 2 MHz, unmodulated, no SAW
		—	-33	—	dBm	Offset = 10 MHz, unmodulated, no SAW
RXBWF	Receiver Bandwidth in FSK Mode ⁽²⁾	50	—	250	kHz	Single side BW, Polyphase Off
RXBWU	Receiver Bandwidth in OOK Mode ⁽²⁾	50	—	400	kHz	Single side BW, Polyphase On
ITP3	Input Third Order Intercept Point	—	-28	—	dBm	Interferers at 1 MHz and 1.950 MHz offset
TSRWF	Receiver Wake-up Time	—	280	500	μs	From FS to Rx ready
TSRWS	Receiver Wake-up Time	—	600	900	μs	From Stand-by to Rx ready
TSRHOP	Receiver Hop Time from Rx Ready to Rx Ready with a Frequency Hop	—	400	—	μs	200 kHz step
		—	400	—	μs	1 MHz step
		—	460	—	μs	5 MHz step
		—	480	—	μs	7 MHz step
		—	520	—	μs	12 MHz step
		—	550	—	μs	20 MHz step
		—	600	—	μs	27 MHz step
RSSIST	RSSI Sampling Time	—	—	$1/f_{dev}$	s	From Rx ready
RSSTDR	RSSI Dynamic Range	—	70	—	dB	Ranging from sensitivity

Note 1: Guaranteed by design and characterization.

2: This reflects the whole receiver bandwidth, as described by conditions for active and passive filters.

TABLE 4-6: TRANSMITTER AC CHARACTERISTICS⁽¹⁾

Symbol	Description	Min	Typ	Max	Unit	Condition
RFOP	RF Output Power, Programmable with 8 Steps of typ. 3 dB	—	+12.5	—	dBm	Maximum power setting
		—	-8.5	—	dBm	Minimum power setting
PN	Phase Noise	—	-112	—	dBc/Hz	Measured with a 600 kHz offset at the transmitter output
TXSP	Transmitted Spurious	—	—	-47	dBc	At any offset between 200 kHz and 600 kHz, unmodulated carrier, $f_{dev} = 50$ kHz
Tx2	Second Harmonic	—	—	-40	dBm	No modulation, see Note ⁽²⁾
Tx3	Third Harmonic					
Tx4	Fourth Harmonic					
Txn	Harmonics above Tx4					
FSKDEV	FSK Deviation	±33	±55	±200	kHz	Programmable
TSTWF	Transmitter Wake-up Time	—	120	500	µs	From FS to Tx ready
TSTWS	Transmitter Wake-up Time	—	600	900	µs	From Stand-by to Tx ready

Note 1: Guaranteed by design and characterization.

2: Transmitter in-circuit performance with SAW filter and crystal.

4.1 Timing Specification and Diagram

TABLE 4-7: SPI TIMING SPECIFICATION^(1,2)

Parameter	Min	Typ	Max	Unit	Condition
SPI Configure Clock Frequency	—	—	6	MHz	—
SPI Data Clock Frequency	—	—	1	MHz	—
Data Hold and Setup Time	2	—	—	µs	—
SDI Setup Time for SPI Configure	250	—	—	ns	—
SDI Setup Time for SPI Data	312	—	—	ns	—
$\overline{\text{CSCON}}$ Low to SCK Rising Edge; SCK Falling Edge to $\overline{\text{CSCON}}$ High	500	—	—	ns	—
$\overline{\text{CSDATA}}$ Low to SCK Rising Edge; SCK Falling Edge to $\overline{\text{CSDATA}}$ High	625	—	—	ns	—
$\overline{\text{CSCON}}$ Rising to Falling Edge	500	—	—	ns	—
$\overline{\text{CSDATA}}$ Rising to Falling Edge	625	—	—	ns	—

Note 1: Typical Values: $T_A = 25^\circ\text{C}$, $V_{IN} = 3.3\text{V}$, Crystal Frequency = 12.8 MHz, unless otherwise specified.

2: Negative current is defined as the current sourced by the pin.

MRF89XAM9A

NOTES:

APPENDIX A: REVISION HISTORY

Revision A (July 2011)

This is the Initial release of the document.

MRF89XAM9A

NOTES:

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